



Click [here](#) for the 3D model.

Dimensions

Chip Size	0805
L	2.01mm +0.81/-0.25mm (0.079 in +0.032/-0.01 in)
W	1.27mm +0.68/-0.25mm (0.05 in +0.027/-0.01 in)
T	1.57mm MAX (0.062 in MAX)
B	0.51mm +/-0.25mm (0.02 in +/-0.01 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	100

General Information

Series	SMD MIL BP PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov
Termination	Solder Dipped
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	470 pF
Capacitance Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)